

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier		User Part Number				
Nexperia B.V.		PESD3V3Z1BCSF				
Name of Laboratory		Part Description				
Assembly reliability labs		NXP ICN8 Protection INDI BD package				
Test	Test Conditions	Duration	# Lots	# Quantity	# Rejects	
# 1	TEST Pre- and Post-Stress Electrical Test Tamb = 25 °C	N/A	see below	all parts	see below	
# 5	HTRB High Temperature Reverse Bias MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	92	4040	0	
# 7	TC Temperature Cycling JESD22-A104 -40 °C to 125°C	1000 cycles	157	6880	0	
# 8 or	UHAST Unbiased HAST JESD22-A118 Tamb = 130 °C, RH = 85 %	96 hours	n.a.	n.a.	n.a.	
# 8a	AC Autoclave JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)					
# 9	HAST Highly Accelerated Stress Test JESD22-A110 Tamb = 130 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1]	96 hours	156	6840	0	
# 10	IOL Intermittent Operating Life MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.	
# 20	RSH Resistance to Solder Heat JESD22-A111 260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.	
# 21	SD Solderability J-STD-002		8	240	0	

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5)
Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
NXP ICN8	Protection INDI	4040	0	1,1	9,51E+08

© 2024 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.